



Material Content Data Sheet



Sales Product Name		BSB012NE2LXI		Issued		29. August 2013			
MA#		MA001050800							
Package		MG-WDSO-N-2-8		Weight*		82.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.494	4.22	4.22	42179	42179	
leadframe	non noble metal	copper	7440-50-8	74.415	89.84	89.84	898298	898298	
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.25		2549		
	noble metal	silver	7440-22-4	0.840	1.01	1.26	10140	12689	
plating	non noble metal	nickel	7440-02-0	0.211	0.25	0.25	2549	2549	
glue	plastics	epoxy resin	-	0.160	0.19		1936		
	noble metal	silver	7440-22-4	0.985	1.19	1.38	11895	13831	
solder	non noble metal	copper	7440-50-8	0.011	0.01		133		
	noble metal	silver	7440-22-4	0.066	0.08		795		
	non noble metal	tin	7440-31-5	2.119	2.56	2.65	25574	26502	
passivation	plastics	epoxy resin	-	0.327	0.40	0.40	3952	3952	
*deviation	< 10%					Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com